

Part Number

Customer

| Category      |      | Parameter                       | Specification                                                                                                                                                           | Measurement Method            |
|---------------|------|---------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------|
| OverallWafer  | 1.0  | Diameter                        | 100.00 +/- 0.30 mm                                                                                                                                                      |                               |
|               | 2.0  | Primary Flat Orientation        | {110} +/- 0.5 degree                                                                                                                                                    | Wafer Vendor                  |
|               | 3.0  | Primary Flat Length             | 32.50 +/- 2.50 mm                                                                                                                                                       | Wafer Vendor                  |
|               | 5.0  | Secondary Flat Length           | None                                                                                                                                                                    | Wafer vendor                  |
|               | 6.0  | Overall Thickness               | 500.00 +/- 12.00 µm                                                                                                                                                     | ADE, 100%                     |
|               | 7.0  | Total Thickness Variation (TTV) | <5.00µm                                                                                                                                                                 | Guaranteed by Process         |
|               | 8.0  | Bow                             | <20.00µm                                                                                                                                                                | ADE to ASTM F534, 20%         |
|               | 9.0  | Warp                            | <20.00µm                                                                                                                                                                | ADE to ASTM F657, 20%         |
|               | 10.0 | Edge Chips                      | 0                                                                                                                                                                       | Bright Light, 100% (note 2)   |
|               | 11.0 | Edge Exclusion                  | 5mm                                                                                                                                                                     |                               |
|               | 12.0 | Edge Rounding                   | Round with STANDARD EDGE                                                                                                                                                | IceMOS proprietary processing |
|               | 13.0 | Handle Growth Method            | CZ                                                                                                                                                                      | Wafer Vendor                  |
| HandleSilicon | 14.0 | Handle Orientation              | {100} +/- 0.5 degree                                                                                                                                                    | Wafer Vendor                  |
|               | 15.0 | Handle Thickness                | 500.00 +/- 12.00 µm                                                                                                                                                     | ADE, 100%                     |
|               | 16.0 | Handle Doping Type              | P                                                                                                                                                                       | Wafer Vendor                  |
|               | 17.0 | Handle Dopant                   | Boron                                                                                                                                                                   | Wafer Vendor                  |
|               | 18.0 | Handle Resistivity              | 1 - 10 Ohmcm                                                                                                                                                            | Wafer Vendor                  |
|               | 19.0 | Backside Finish                 | Polished with chuck marks and handling per additional comments. With Laser Mark. Laser Mark Format [BACK], shallow scribe located along the flat on the wafer backside. | Guaranteed by process         |
|               | 20.0 | Total LPD Count                 | <30.00pcs                                                                                                                                                               | Bright Light, 100% (note 2)   |
|               | 21.0 | Total scratch length            | Front side <10mm total length                                                                                                                                           | Bright Light, 100% (note 2)   |
|               | 22.0 | Surface Haze                    | none                                                                                                                                                                    | Bright Light, 100% (note 2)   |

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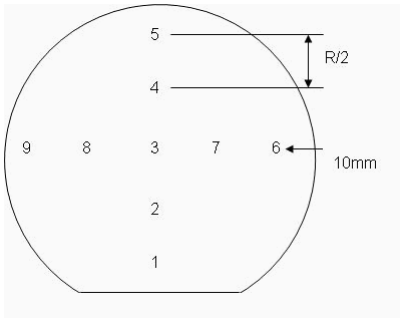
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|                  |                   |                                                                                         |                                                                                     |
|------------------|-------------------|-----------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------|
| Shipping Details | Wafer per box :   | Max 25                                                                                  |  |
|                  | Packaging :       | Taped Polypropylene Wafer Box<br>Empak, Ultrapak, 100.00mm<br>Antistatic Double Bagging |                                                                                     |
|                  | Lot Shipment Data | Device Thickness<br>Bow / Warp Data<br>Handle and SOI Thickness                         |                                                                                     |

|                   |                                                                                  |  |  |
|-------------------|----------------------------------------------------------------------------------|--|--|
| Explanatory Notes | 1. Microscope inspection performed using microscope scan as below. 5x objective. |  |  |
|-------------------|----------------------------------------------------------------------------------|--|--|

|  |                                                                                                                                                                                               |  |  |
|--|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--|--|
|  | 2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523. |  |  |
|--|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--|--|

|  |                                                           |  |  |
|--|-----------------------------------------------------------|--|--|
|  | 3. 9 point measurement are as shown in the diagram below: |  |  |
|--|-----------------------------------------------------------|--|--|



Additional Information